

**NEW UTILITY PATENT APPLICATION  
TRANSMITTAL**

DOCKET NO.  
END920020084US2 (IEN-10-5695-D1)

TOTAL PAGES IN THIS SUBMISSION  
3

22154 U.S. PTO  
10/660261  
09/11/03

**TO MAIL STOP PATENT APPLICATION**  
**COMMISSIONER FOR PATENTS**

P.O. Box 1450

Alexandria, VA 22313-1450

Transmitted herewith for filing under 35 USC 111(a) and 37 CFR 1.53(b) is a new utility patent application for an invention entitled:

**SEMICONDUCTOR CHIP MODULE AND METHOD OF  
MANUFACTURE OF SAME**

invented by:

WILLIAM INFANTOLINO  
VOYA R. MARKOVICH  
SANJEEV B. SATHE  
GEORGE H. THIEL

assigned to

INTERNATIONAL BUSINESS MACHINES CORPORATION  
Armonk, New York

**If a CONTINUATION APPLICATION, check appropriate box and supply the requisite information:**

☐ Continuation

☒ Divisional

☐ Continuation -in -part (CIP)

in prior application No.: 10/254,414

Enclosed are:

Application Elements

1. ☒ Filing fee as calculated and transmitted as described below
2. ☒ Specification having 13 pages and including the following:
  - a. ☒ Descriptive Title of the Invention
  - b. ☒ Cross References to Related Applications (*if applicable*)
  - c. ☐ Statement Regarding Federally-sponsored Research/Development (*if applicable*)
  - d. ☐ Reference to Microfiche Appendix (*if applicable*)
  - e. ☒ Background of the Invention
  - f. ☒ Brief Summary of the Invention
  - g. ☒ Brief Description of the Drawings (*if drawings filed*)
  - h. ☒ Detailed Description
  - i. ☒ Claim(s) as Classified Below
  - j. ☒ Abstract of the Disclosure
3. ☒ Drawing(s) (*when necessary as prescribed by 35 USC 113*)
  - a. ☒ Formal
  - b. ☐ InformalNumber of Sheets 3

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4. ☒ Oath or Declaration
- a. ☐ Newly executed (*original or copy*) ☐ Unexecuted
- b. ☒ Copy from a prior application (37 CFR 1.63(d)) (*for continuation/divisional application only*)
- c. ☒ With Power of Attorney ☐ Without Power of Attorney

Application Elements (Continued)

5. ☐ Incorporation by Reference (*usable if Box 4b is checked*)  
The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied under Box 4b, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.
6. ☐ Computer Program in Microfiche (*Appendix*)
7. ☐ Nucleotide and/or Amino Acid Sequence Submission (*if applicable, all must be included*)
- a. ☐ Paper Copy
- b. ☐ Computer Readable Copy (*identical to computer copy*)
- c. ☐ Statement Verifying Identical Paper and Computer Readable Copy

Accompanying Application Parts

8. ☐ Assignment Papers (*cover sheet & document(s)*)  
International Business Machines Corporation, Armonk, NY
9. ☐ 37 CFR 3.73(B) Statement (*when there is an assignee*)
10. ☐ English Translation Document (*if applicable*)
11. ☒ Information Disclosure Statement/PTO-1449 ☐ Copies of IDS Citations
12. ☐ Preliminary Amendment
13. ☒ Return Receipt Postcards - 2
14. ☒ Certificate of Mailing  
☐ First Class ☒ Express Mail (*Specify Label No.*): EL 897035585 US
15. ☒ Application Data Sheet
16. ☐ Additional Enclosures (*please identify below*):

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**FEE CALCULATION AND TRANSMITTAL**

**CLAIMS AS FILED**

1) For	2) Number Filed	3) Number Extra	Rate	Additional Fee
TOTAL CLAIMS (37 CFR 1.16(c))	8-20 =	- 0 -	x\$18.00	- 0 -
INDEPENDENT CLAIMS (37 CFR 1.16(c))	1 - 3 =	- 0 -	x \$80.00	- 0 -
First Pres. Of Multiple Dep. Claims	= 0			\$ 0.00
Basic Fee	= 0			\$ 750.00
			TOTAL	\$ 750.00

- ☐ A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 09-0457 as described below. A duplicate copy of this sheet is enclosed.
- ☒ Charge the amount of \$750.00 as filing fee.
- ☒ Credit any overpayment or any deficiency.
- ☒ Charge any additional filing fees required under 37 CFR 1.16 and 1.17.

Respectfully submitted,

Date: Sept 11, 2003

By: William N. Hogg

William N. Hogg, Reg. No. 20,156  
Driggs, Lucas, Brubaker & Hogg Co., L.P.A.  
8522 East Avenue  
Mentor, Ohio 44060  
(440) 205 3600  
Fax: 440 205 3601  
e-mail: bill@driggslaw.com

WNH:cg

CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10) Applicant(s): Infantolino et al			DOCKET NO. END920020084US2 (IEN-10-5695-D1)
Serial No. To be assigned	Filing Date Filed Herewith	Examiner	Group Art Unit
Invention: SEMICONDUCTOR CHIP MODULE AND METHOD OF MANUFACTURE OF SAME			
<p>           I hereby certify that the attached <b><u>Divisional Patent Application and Supporting Documents</u></b> are being deposited with the United States Postal Service "as Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on <u>September 11, 2003</u>.         </p> <div style="text-align: center;"> <p> <u>CAROLE GIACOMAZZO</u>            (Typed or Printed Name of Person Mailing Correspondence)         </p> <p> <u>Carole Giacomazzo</u>            (Signature of Person Mailing Correspondence)         </p> <p> <u>EL 897035585 US</u>            ("Express Mail" Mailing Label Number)         </p> </div>			